Amendments to the Claims:

Without prejudice, this listing of the claims replaces all prior versions and listings of the claims in the present application:

Listing of Claims:

1. (Currently Amended) A method for producing a conductive layered coating on an insulating substrate, comprising:

equipping, in selected regions, at least one surface of an electrically insulating substrate with a coating of an electrically highly conductive first metal, the coating being structured as conductor paths;

cleaning the at least one coated surface;

seeding the coating with seeds of a second metal;

depositing a layer including an alloy of the second metal onto the coating seeded with the seeds of the second metal;

firing the substrate deposited with the layer of the second metal to form the conductive layered coating, the firing being performed at a temperature below the melting point of the first metal, the second metal and the alloy; and

contacting a gold bonding wire to the ~~first metal~~ conductive layered coating,

wherein:

the substrate includes ~~one of a ceramic and~~ an LTCC,

the first metal includes silver, and

the second metal includes palladium.

2. (Canceled)

3. (Canceled)

4. (Previously Presented) The method as recited in Claim 1, wherein:

in the depositing of the layer of the second metal, palladium is deposited at a ratio of from 0.1 to 50% percent by weight of the alloy.

5. (Previously Presented) The method as recited in Claim 1, wherein:

in the depositing of palladium, the palladium is deposited in such a way that a concentration of greater than 20% percent by weight palladium in the alloy results.

6. (Original) The method as recited in Claim 1, wherein:

the seeding and the depositing are performed according to an electroless procedure.

7. (Original) The method as recited in Claim 1, wherein:

the firing is performed at a temperature between 830 and 870°C.

8. (Original) The method as recited in Claim 1, wherein:

the firing is performed at a temperature of 850°C.

9 -10. (Canceled)

11. (New) A method for producing a conductive layered coating on an electrically insulating substrate, comprising:

equipping, in selected regions, at least one surface of the electrically insulating substrate with a coating of a first metal structured as a conductor path;

cleaning the at least one coated surface;

seeding the at least one coated surface with seeds of a second metal;

depositing a layer including an alloy of the second metal onto the at least one seeded coated surface; and

firing the substrate deposited with the layer to form the conductive layered coating, the firing being performed at a temperature below the melting point of the first metal, the second metal and the alloy.

12. (New) The method of claim 11, wherein substrate include an LTCC;

13. (New) The method of claim 12, wherein the first metal includes silver and the second metal include palladium.

14. (New) The method of claim 13, further comprising:

contacting a gold bonding wire to the conductive coating.